PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	MDG/22/13306
1.3 Title of PCN	STM32G03 and STM32G04 64K - product enhancement
1.4 Product Category	STM32G030x, STM32G031x, STM32G04x
1.5 Issue date	2022-04-26

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
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2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC FAB14 (Taiwan) ST Crolles (France)

4. Description of change

	Old	New
4.1 Description	STM32G030x, STM32G031x and STM32G04x - (Die466 – cut1.1 revision Z) product has limitation as described in Errata Sheets. - ES0486 (Rev 3 - Feb 2021) for STM32G030 device - ES0487 (Rev 3 - Feb 2021) for STM32G031 device - ES0488 (Rev 3 - Feb 2021) for STM32G04 device What are the limitations: 1. Device lock in case of OPT bytes mismatch 2. Flash memory PCROP area weakness (STM32G030 device not concerned) 3. TIM16 and TIM17 are unduly clocked by SYSCLK 4. ADC Offset calibration improvements 5. Under RDP Level 1, booting from Main Flash memory selected through PA14 BOOT0 pin is not functional 6. DMAMUX cannot be synchronized or triggered by EXTI	STM32G030x, STM32G031x and STM32G04x - (Die466 – cut1.2 revision Y) product enhancement fixes those limitations as described in Errata Sheet. - ES0486 (Rev 4 - Apr 2022) for STM32G030 device - ES0487 (Rev 4 - Apr 2022) for STM32G031 device - ES0488 (Rev 4 - Apr 2022) for STM32G04 device What are the enhancements: 1. Device lock in case of OPT bytes mismatch - fixed 2. Flash memory PCROP area weakness – fixed (note STM32G030 device is not concerned by this issue) 3. TIM16 and TIM17 are unduly clocked by SYSCLK - fixed 4. ADC Offset calibration improved 5. Under RDP Level 1, booting from Main Flash memory selected through PA14 BOOT0 pin is functional 6. DMAMUX can be synchronized or triggered by EXTI 7. Device IDCODE updated
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Impact on functionality as indicated in Errata Sheets: ES0486, ES0487 & ES0488	

5. Reason / motivation for change

5.1 Motivation	Improvements was implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "Z" to "Y" on Package Marking

7. Timing / schedule	
7.1 Date of qualification results	2022-03-30
7.2 Intended start of delivery	2022-05-26
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	13306 MDG-MCD-RER1808 V2 - STM32G031x - Die 466XXXY - Reliability evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2022-04-26

9. Attachments (additional documentations)
13306 Public product.pdf 13306 MDG-MCD-RER1808 V2 - STM32G031x - Die 466XXXY - Reliability evaluation report.pdf 13306 PCN13306_Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32G031F8P6	
	STM32G031G6U6	
	STM32G031G8U6	
	STM32G031K8T6	

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